

Abstract

A method of fabricating an inkjet printhead chip which includes the step of fabricating drive circuitry layers on a substrate with a CMOS fabrication process. A first sacrificial layer is deposited on the substrate. A heater layer for heating circuits is deposited on the  
5 first sacrificial layer and etched to form the heating circuits. A resiliently flexible layer of dielectric material is deposited on the substrate to cover the heater layer and etched to form actuators and ink ejection members. A second sacrificial layer is deposited on the substrate to cover the actuators and the ink ejection members and etched to define deposition zones for the nozzle chamber walls and the roof walls. A layer of a structural  
10 material is deposited on the second sacrificial layer to form the nozzle chamber walls and the roof walls. The sacrificial layers are finally etched away.